

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)
 Contact Info: ti.com/support
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
 Created on: 06/08/2022

Details for "TLV117118DCYR"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
TLV117118DCYR	SN	Level-1-260C-UNLIM	Ext-Mfg	DCY 4	6.5x3.5x1.6	77.1

***Total Device Mass**

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Copper and Its Alloys	Copper	7440-50-8	0.067332	97.199446	971994	0.087344	873
Copper and Its Alloys	Iron	7439-89-6	0.000001	0.001444	14	0.000001	0
Precious Metals	Palladium	7440-05-3	0.001938	2.797667	27977	0.002514	25
Precious Metals	Silver	7440-22-4	0.000001	0.001444	14	0.000001	0
Sub-Total			0.069272	100	1000000	0.089861	899
Die Attach Adhesive							
Other Inorganic Materials	Aluminum Oxide	1344-28-1	0.015593	30.000385	300004	0.020228	202
Other Inorganic Materials	Silica	7631-86-9	0.002339	4.500154	45002	0.003034	30
Other Organic Materials	Chlorine	7782-50-5	0.000018	0.034631	346	0.000023	0
Thermoplastics	Epoxy	85954-11-6	0.034026	65.46483	654648	0.044139	441
Sub-Total			0.051976	100	1000000	0.067424	674
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	4.738386	97.437488	974375	6.146729	61467
Copper and Its Alloys	Iron	7439-89-6	0.114281	2.35001	23500	0.148248	1482
Copper and Its Alloys	Phosphorus	7723-14-0	0.004012	0.0825	825	0.005204	52
Other Nonferrous Metals and Alloys	Lead	7439-92-1	0.000243	0.004997	50	0.000315	3
Zinc and Its Alloys	Zinc	7440-66-6	0.006079	0.125005	1250	0.007886	79
Sub-Total			4.863001	100	1000000	6.308382	63084
Lead Frame Plating							
Other Nonferrous Metals and Alloys	Tin	7440-31-5	0.004	100	1000000	0.005189	52
Sub-Total			0.004	100	1000000	0.005189	52
Mold Compound							
Not Categorized	Phenolic Resin	9003-35-4	3.582871	5	50000	4.647772	46478
Other Inorganic Materials	Silica	7631-86-9	62.234469	86.85	868500	80.7318	807318
Other Plastics and Rubber	Carbon Black	1333-86-4	0.107486	0.15	1500	0.139433	1394
Thermoplastics	Epoxy	85954-11-6	5.732594	8.000001	80000	7.436436	74364
Sub-Total			71.65742	100	1000000	92.955441	929554
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	0.442255	100	1000000	0.573702	5737
Sub-Total			0.442255	100	1000000	0.573702	5737
Total			77.087924			100	1000000

Important Note

The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.

The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.

[See Glossary of Terms for more details.](#)

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSiS or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

[For an explanation of the methods used to determine material weights, See Product Content Methodology](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

[For additional information, please contact TI customer support.](#)

[Signature: \(click here for a fuller statement with a signed certificate\)](#)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality
 For further environmental statements, please go to www.ti.com/eoinfo
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RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.